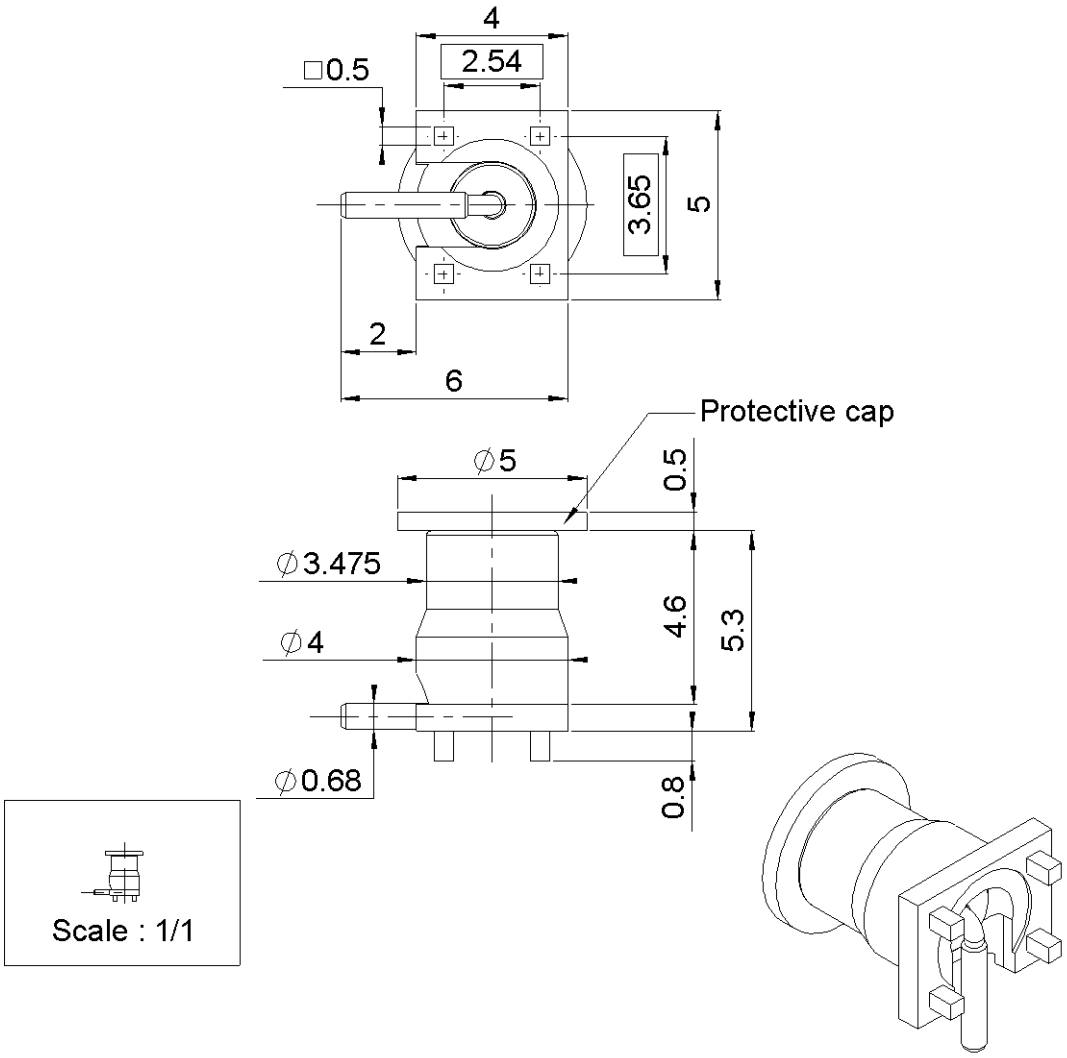
PAGE **1/5**	ISSUE **1435C**	SERIES **MMCX**	PART NUMBER **R110427830**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NPGR**
Center contact	**BERYLLIUM COPPER**	**GOLD OVER NICKEL**
Outer contact	**-**	**-**
Insulator	**PTFE**	
Gasket	**-**	
Others parts	**-**	**-**
-	**-**	**-**
-	**-**	**-**

PACKAGING

Standard	Unit	Other
500	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-6**	GHz
VSWR	**NA**	**+**	**0.0000**	x F(GHz) Maxi
Insertion loss			**NA**	√F(GHz) dB Maxi
RF leakage		- (		- F(GHz)) dB Maxi
Voltage rating			**250**	Veff Maxi
Dielectric withstanding voltage			**500**	Veff mini
Insulation resistance			**1000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**10***	N mini
Axial force – Opposite end	**10***	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**500**	Cycles mini
Weight	**0.3800**	g

ENVIRONMENTAL

Operating temperature	**-55/+155**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

1AB052720013

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***after soldering**

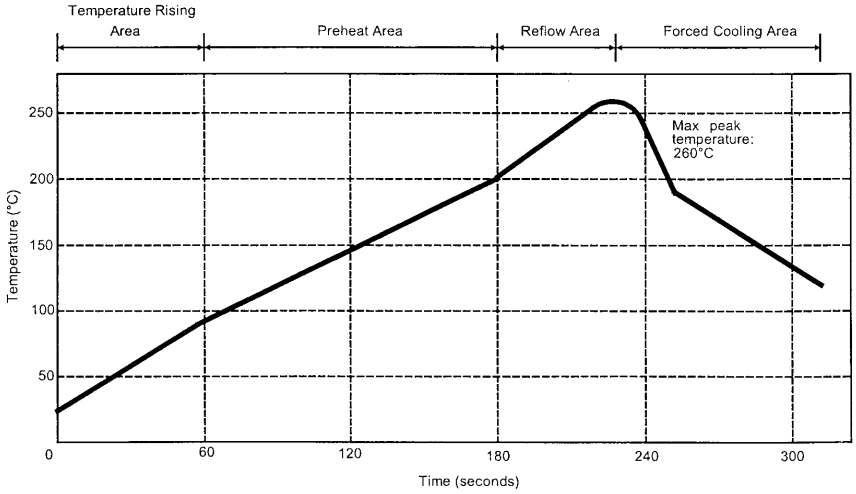
Materials are compliant with the EU's RoHS directive

SOLDER PROCEDURE

1. **Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.**
   We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. **Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.**
3. **This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.**
4. **The cleaning of printed circuit boards is not obliged .**
5. **Verification of solder joints and position of the component by visual inspection.**

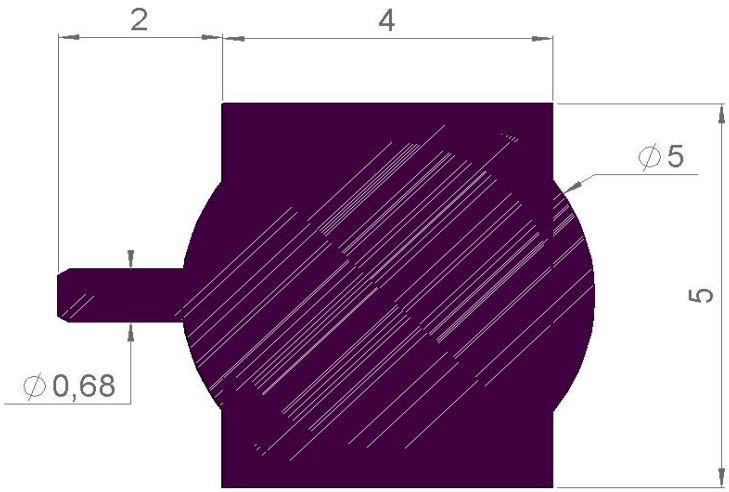
NOTE : The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE

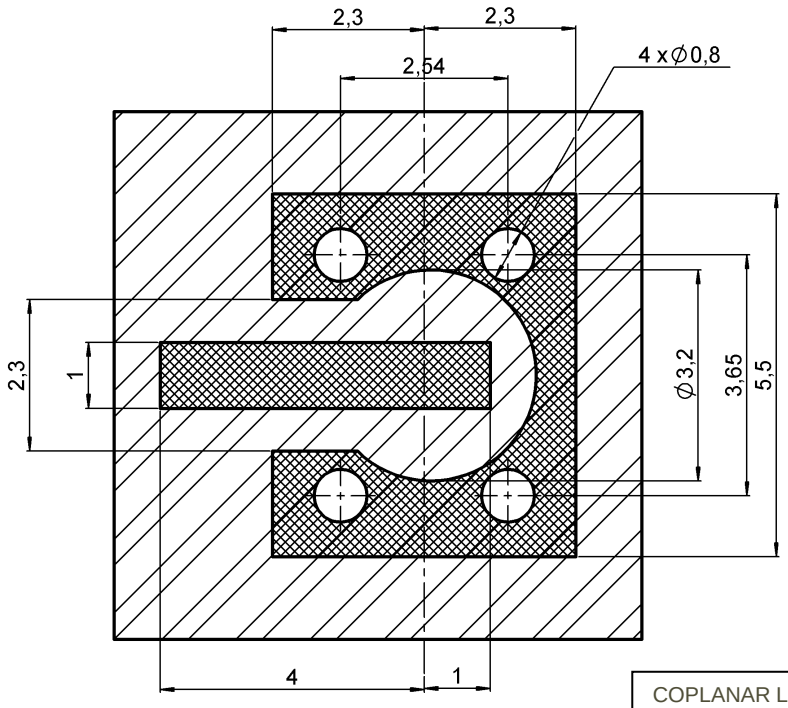


Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

SHADOW OF RECEPTACLE FOR VIDEO CAMERA



STANDARD PAD



Masse + vernis
Ground + varnish

Plots de soudure
Lands for solder paste

COPLANAR LINE
Pattern and signal are on the same side.
Thickness of the PCB : 1.6 mm
The material of the PCB is the epoxy resin of
Glass fabrics bacs (ER : 4.8).
The solder resist should be printed except for
The land pattern on the PCB.